

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

MSCP

LT3020IMS8#PBF

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TOTAL MASS (g): 0.027052

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001815	1000000	670923075		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.010433	975000	38564.25		
		Iron (Fe)	7439-89-6	0.000257	24000	9500.2128062		
		Phosphorus (P)	7723-14-0	0.000003	300	110.897422791		
		Zinc (Zn)	7440-66-6	0.000007	700	258.760650635		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.010700</b>	<b>1000000</b>	<b>39554.15625</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.000710	1000000	26246.6464844		
<b>External Plating Total:</b>						<b>0.000710</b>	<b>1000000</b>	<b>26246.6464844</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000086	1000000	3179.05932617		
<b>Internal Plating Total:</b>						<b>0.000086</b>	<b>1000000</b>	<b>3179.05932617</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000668	750000	24093.1621094		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000223	250000	8243.375		
		<b>Die Attach Total:</b>				<b>0.000891</b>	<b>1000000</b>	<b>32936.53125</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.001659	130000	61326.2734375
Bromine (Br)	40039-09-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.010591	830000	391504.875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000447	35000	16523.7148438		
Carbon Black (C)	1333-86-4			0.000064	5000	2365.81176758		
<b>Encapsulation Total:</b>						<b>0.012761</b>	<b>1000000</b>	<b>471720.65625</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000089	1000000	3289.95678711		

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